



ORIENT

Photo coupler

Product Data Sheet

Name: ORPC-845

Customer: _____

Date: _____

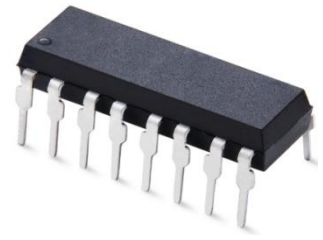
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1. Features

- (1) Current conversion ratio
- (2) (CTR:600%—7500% working condition $I_F = 1\text{mA}$, $V_{CE} = 2\text{V}$)
- (3) Insulation Voltage = 5,000Vrms.
- (4) Response Time
- (5) tr: TYP.60 μs ; tf: TYP. 53 μs (@ $V_{CE} = 2\text{V}$, $I_C = 10\text{mA}$, $R_L = 100\Omega$)
- (6) Safety approval
 - UL approved (No.E323844)
 - VDE approved (No.40029733)
- (7) In compliance with RoHS, REACH standards
- (8) MSL Level 1

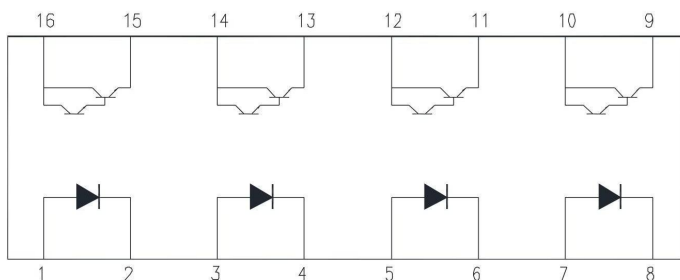
2. Instructions

- (1) ORPC-845 series optical coupler consists of four infrared emitting diodes and four optically to a photo Darlington detector.
- (2) Pin pitch of ORPC-845 is 2.54mm

3. Application Range

- (1) Telephone set,telephone exchangers
- (2) Sequence controllers
- (3) System appliances,measuring instruments
- (4) Signal transmission between circuits of different potentials and impedances

4. Functional Diagram



1,3,5,7 Anode 9,11,13,15 Emitter
 2,4,6,8 Cathode 10,12,14,16 Collector

5. Absolute Maximum Ratings (Ta=25°C)

Parameter		Symbol	Rated Value	Unit
Input	Forward Current	I_F	50	mA
	Peak forward current(1us pulse)	I_{FP}	1	A
	Reverse Voltage	V_R	6	V
	Consume Power	P	70	mW
Output	Collector and emitter Voltage	V_{CEO}	80	V
	Emitter and collector Voltage	V_{ECO}	7	
	Collector Current	I_C	80	mA
	Consume Power	P_C	150	mW
	Total Consume Power	P_{tot}	200	mW
*1 Insulation Voltage		V_{iso}	5,000	Vrms
Working Temperature		T_{opr}	-55 to + 110	°C
Deposit Temperature		T_{stg}	-55 to + 125	
*2 Soldering Temperature		T_{sol}	260	

*1. AC Test, 1 minute, humidity = 40~60%

Isolation voltage shall be measured using the following method.

(1) Short between anode and cathode on the primary side and between collector and emitter on the secondary side.

(2) The isolation voltage tester with zero-cross circuit shall be used.

(3) The waveform of applied voltage shall be a sine wave.

*2. soldering time is 10 seconds

6. Electrical optical characteristics at TA=25°C

Parameter		Symbol	Min	Typ.*	Max	Unit	Condition
Input	Forward Voltage	V_F	---	1.2	1.4	V	$I_F=20mA$
	Reverse Current	I_R	---	---	5	μA	$V_R=5V$
	Collector Capacitance	C_t	---	30	250	pF	$V=0, f=1KHZ$
Output	Collector to emitter Current	I_{CEO}	---	---	1	μA	$V_{CE}=10V,$ $I_F=0mA$
	Collector and Emitter attenuation Voltage	BV_{CEO}	80	---	---	V	$I_C=0.1mA,$ $I_F=0mA$
	Emitter and Collector attenuation Voltage	BV_{ECO}	7	---	---	V	$I_E=0.1mA,$ $I_F=0mA$
Transforming Characteristics	*1Current conversion ratio	CTR	600	---	7500	%	$I_F=1mA,$ $V_{CE}=2V$
	Collector Current	I_C	6	---	75	mA	
	Collector and Emitter Saturation Voltage	$V_{CE(sat)}$	---	0.8	1	V	$I_F=20mA,$ $I_C=5mA$
	Insulation Impedance	R_{iso}	5×10^{10}	1×10^{12}	---	Ω	DC500V 40~60%R.H.
	Capacitance	C_f	---	0.6	1.0	pF	$V=0, f=1MHz$
	Transforming Frequency	f_c	1	6	---	kHz	$V_{CE}=5V,$ $I_C=2mA,$ $R_L=100\Omega, -3dB$
	Rise time	t_r	---	60	300	μs	$V_{CE}=2V,$ $I_C=2mA,$ $R_L=100\Omega$
	Descend Time	t_f	---	53	250	μs	

*1 Current Conversion Ratio = $I_C / I_F \times 100\%$

7. Order Information

Part Number

ORPC-845W-X-Y-Z

Note

W = Lead form option (S, M or none)

X = Lead frame option (F: Iron, C:copper)

Y = 'V' code for VDE safety (This options is not necessary).

Z = 'G' code for Halogen free (This options is not necessary).

* VDE Code can be selected.

* Halogen Free can be selected.

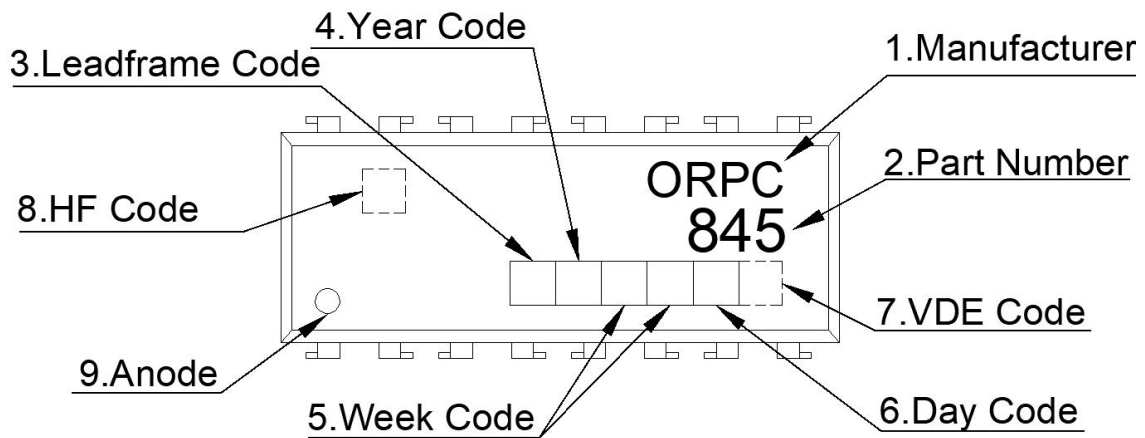
Option	Description	Packing quantity
None	Standard DIP-16	24 units per tube
M	Wide lead bend (0.4 inch spacing)	24 units per tube
S	Surface mount lead form (low profile)	24 units per tube

8. Rank table of current transfer ratio (CTR)

Grade Sign	Min (%)	Max (%)
ORPC-845 NO mark	600	7500

Note: Working condition: IF=5mA, VCE=5V, Ta=25°C

9. Naming Rule



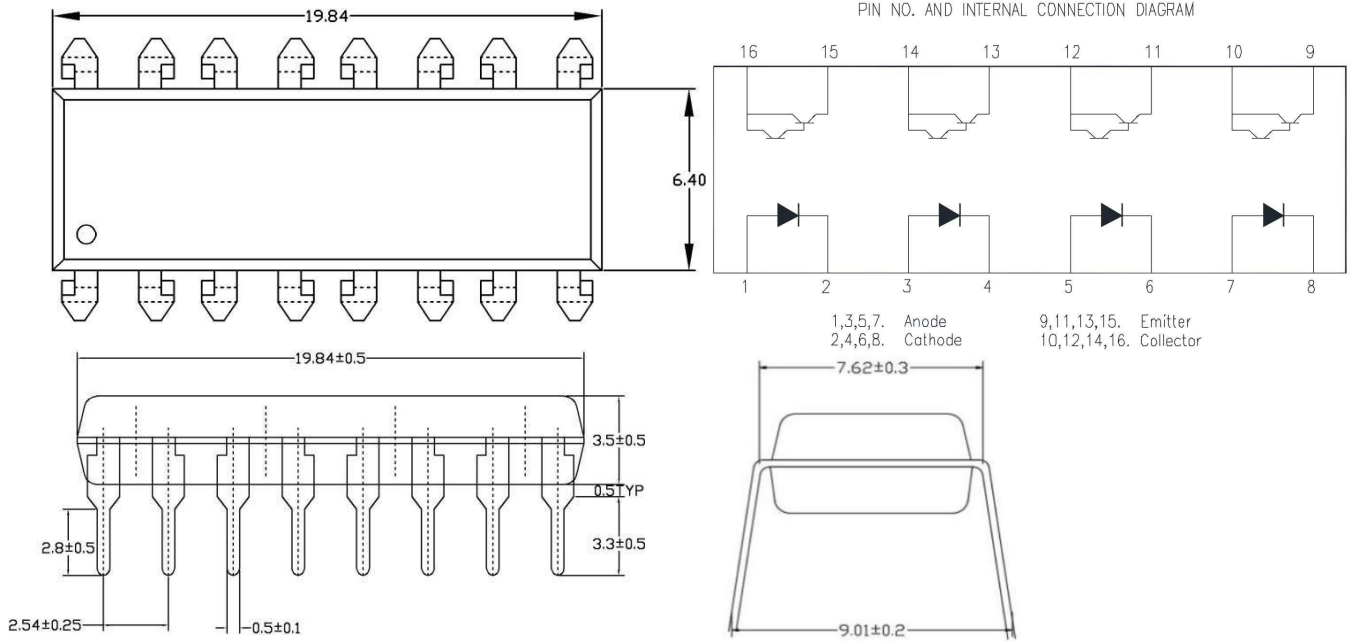
- (1) Manufacturer : ORIENT.
- (2) 845 denotes Part Number.
- (3) Lead frame Code : 'F' means Iron, 'C' means Copper.
- (4) Year Code : '1' means '2021' and so on.
- (5) Week Code : 01 means the first week, 02 means the second week and so on.
- (6) Day Code : "A to G" means "Monday to Sunday"
- (7) VDE Code . (Optional)
- (8) HF Code : Halogen Free. (Optional)
- (9) Anode.

* Halogen Free Mark can be selected.

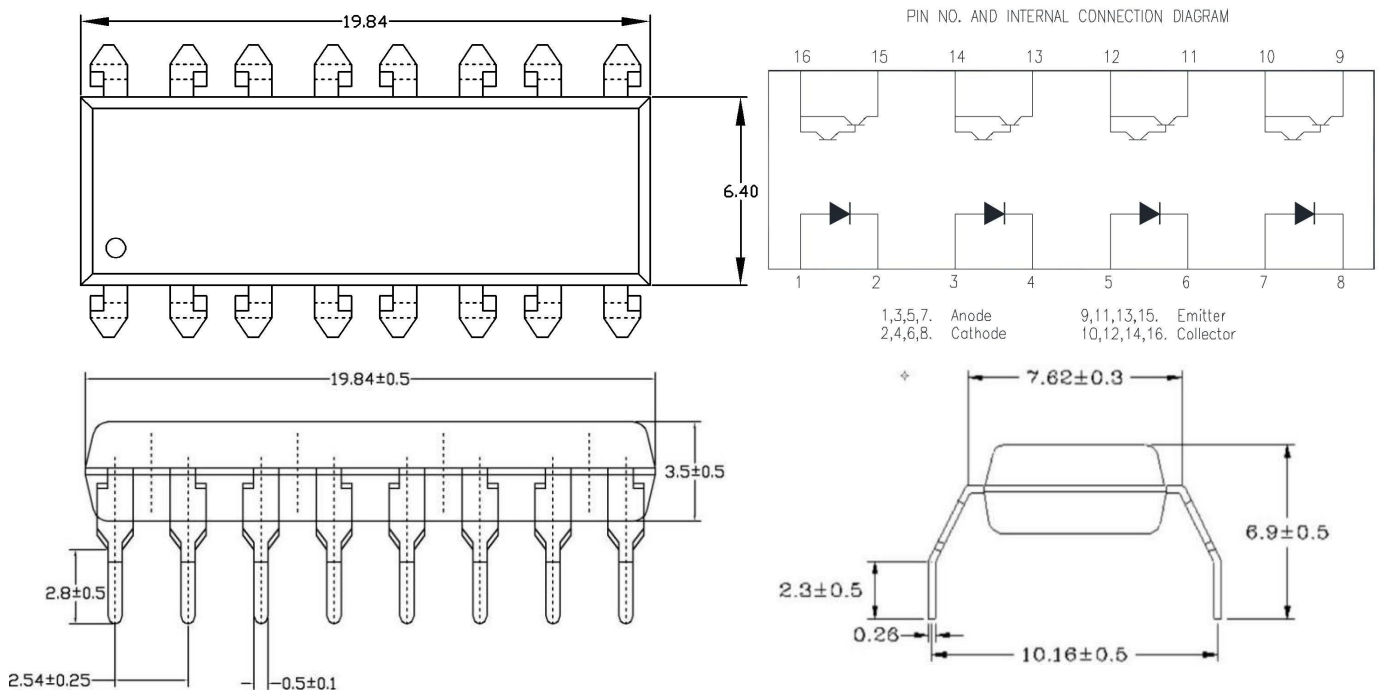
* VDE Mark can be selected.

10. Outer Dimension (Unit: mm)

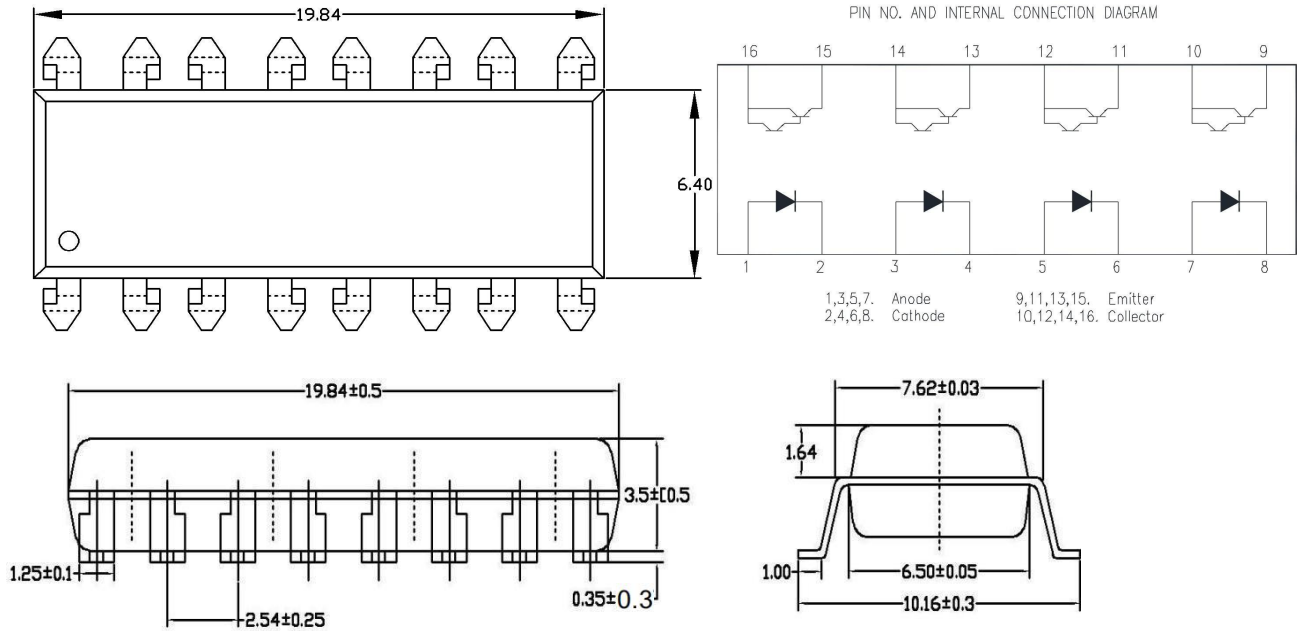
1. ORPC-845



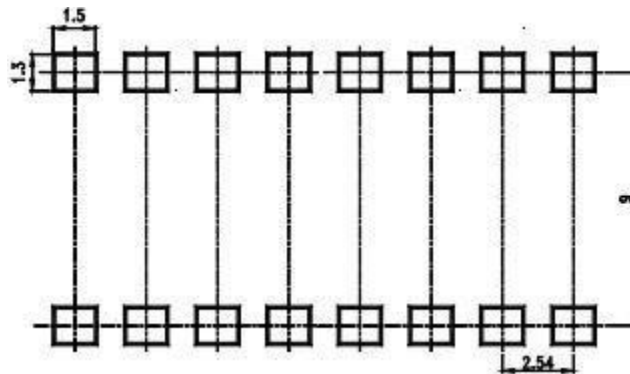
2. ORPC-845M



3. ORPC-845S



11. RECOMMENDED FOOT PRINT PATTERNS (MOUNT PAD)



Unit: mm

12. Package Dimension

(1) package dimension










DIP Type

Packing Information	
Packing type	Tube
Qty per Tube	24pcs
Small box (Inner) Dimension	525*128*60mm
Large box (Outer) Dimension	545*290*335mm
The Amount per Inner Box	1,200pcs
The Amount per Outer Box	12,000pcs

SOP Type

Packing Information	
Packing type	Tube
Qty per Tube	24pcs
Small box (Inner) Dimension	525*128*60mm
Large box (Outer) Dimension	545*290*335mm
The Amount per Inner Box	1,000pcs
The Amount per Outer Box	10,000pcs

(2)Packing Label Sample

 <p>Material Code : 120PCXXXXXX  P/N : OR-XXXXXX  Lot No. : XXXXXX-XXXXX-TX-X  D/C : XXXX  Qty : XXXX PCS </p>	  
<div style="display: flex; justify-content: space-around;"> <div style="border: 1px solid black; width: 80px; height: 80px; text-align: center; line-height: 80px;">内箱码</div> <div style="border: 1px solid black; width: 80px; height: 80px; text-align: center; line-height: 80px;">外箱码</div> </div>	
<p>“XXXXXXXXXXXXXXXX” (一体机序列码) Made in China</p>	

Note:

1. Material Code :Product ID.
2. P/N :Contents with "Order Information" in the specification.
3. Lot No. :Product data.
4. D/C :Product weeks.
5. Quantity :Packaging quantity.

13. Reliability Test

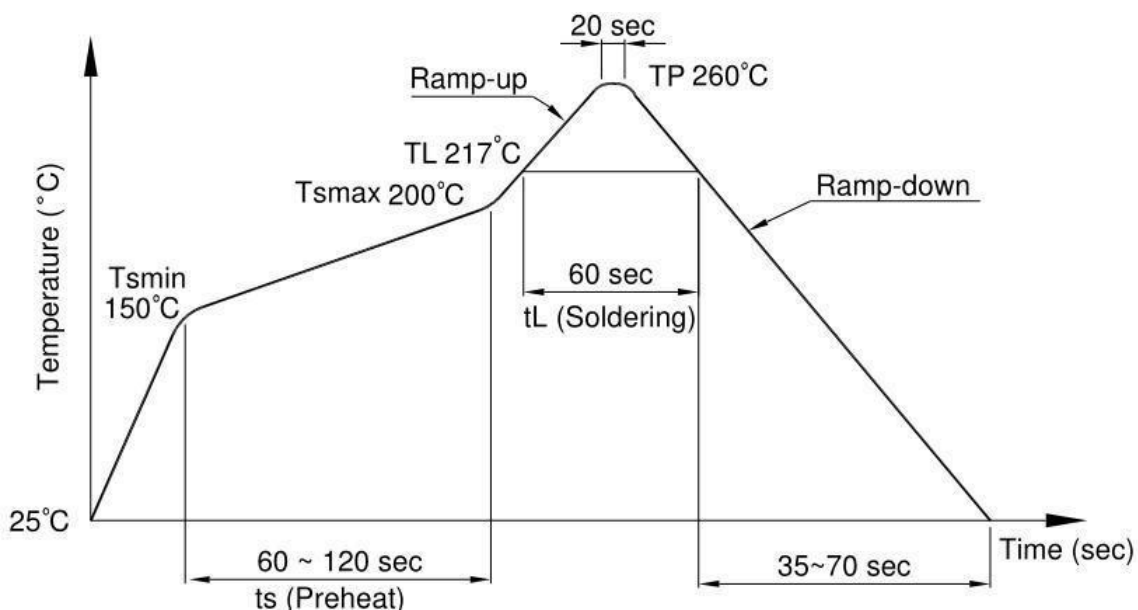
NO.	ITEMS	Reliability Testing				
		QTY. (Pcs)	Condition	Process	Device	Standard
1	RSH 耐焊接热	22	260±5℃	10s/3 次	锡炉	JESD22-A106
2	HTSL 高温存储	77	125℃	168 hrs	高温烤箱 测试仪	JESD22-A103
				500 hrs		
				1000 hrs		
3	LTSL 低温存储	77	-55℃	168 hrs	低温箱 测试仪	JESD22-A119
				500 hrs		
				1000 hrs		
4	TC 温度循环	77	H:125℃ 15min ∫ 5min L:-55℃ 15min	300 cycle	冷热冲击机	JESD22-A104
5	TS 温度冲击	77	H:100℃ 5min ∫ 15s L:-40℃ 5min	300 cycle	冷热冲击机	JESD22-A106
6	HTOL 高温操作	77	110℃ IF=10mA Vce=5V	168 hrs	高温烤箱 测试仪、老 化电路板	JESD22-A108
				500 hrs		
				1000 hrs		
7	ESD-HBM 人体模式	22	≥8KV 1Cycle	1次	ESD静电测 试仪	JESD22-A114
8	SD 可焊性	22	Pb-free 245±5℃	5S/1次	锡炉	JESD22-B102
9	HTRB 高温反向偏压	77	HTRB @125℃ Vce=80v	168 hrs	高温烤箱 , 测试仪	JESD22-A103
				500 hrs		
				1000 hrs		
10	H3TRB 温湿度反向偏 压, 寿命试验	77	H3TRB 85℃,85%RH Vce=80v	168 hrs	恒温恒湿 机, 测试仪	JESD22-A101
				500 hrs		
				1000 hrs		
11	Autoclave 压力锅	77	Ta=121 ℃,100%RH,2atm	96hrs	压力锅	JESD22-A102

14. Temperature Profile Of Soldering

(1) IR Reflow soldering (JEDEC-STD-020C compliant)

One time soldering reflow is recommended within the condition of temperature and time profile shown below.
Do not solder more than three times.

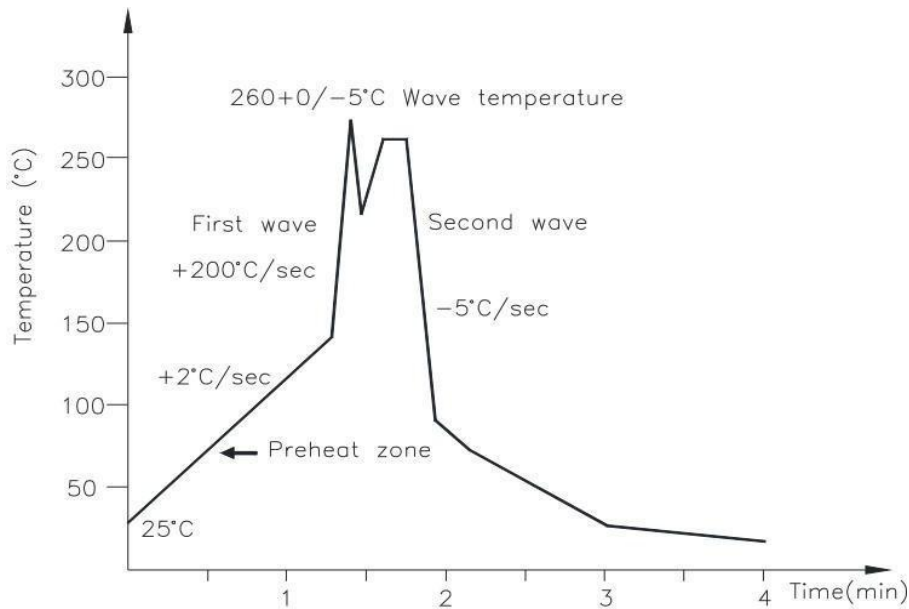
Profile item	Conditions
Preheat	
- Temperature Min (T Smin)	150°C
- Temperature Max (T Smax)	200°C
- Time (min to max) (ts)	90±30 sec
Soldering zone	
- Temperature (TL)	217°C
- Time (t L)	60 sec
Peak Temperature	260°C
Peak Temperature time	20 sec
Ramp-up rate	3°C / sec max.
Ramp-down rate from peak temperature	3~6°C / sec
Reflow times	≤3



(2) Wave soldering (JEDEC22A111 compliant)

One time soldering is recommended within the condition of temperature.

Temperature	260+0/-5°C
Time	10 sec
Preheat temperature	5 to 140°C
Preheat time	30 to 80 sec



(3) Hand soldering by soldering iron

Allow single lead soldering in every single process. One time soldering is recommended.

Temperature	380+0/-5°C
Time	3 sec max

15. Characteristics Curv

Fig.1 Forward Current vs. Ambient Temperature

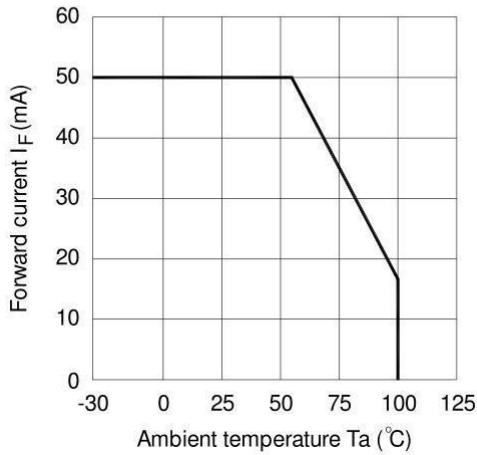


Fig.2 Collector Power Dissipation vs. Ambient Temperature

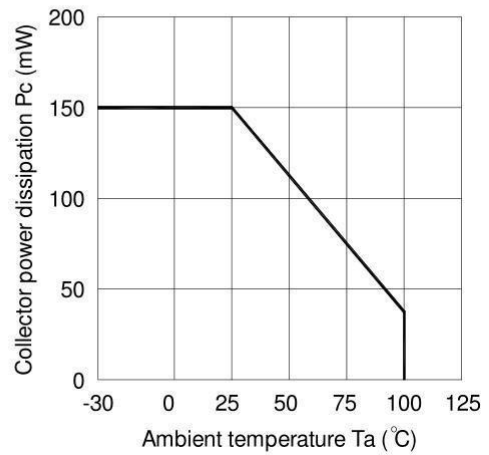


Fig.3 Collector-emitter Saturation Voltage vs. Forward Current

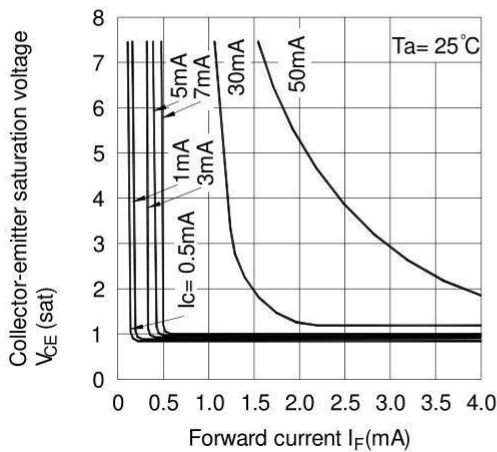


Fig.4 Forward Current vs. Forward Voltage

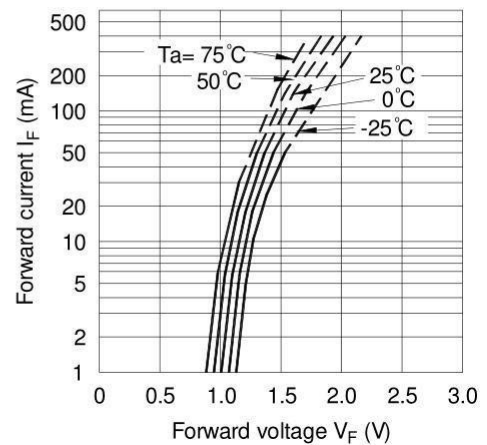


Fig.5 Current Transfer Ratio vs. Forward Current

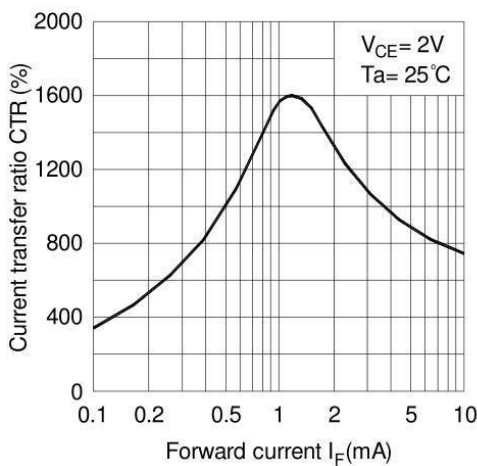


Fig.6 Collector Current vs. Collector-emitter Voltage

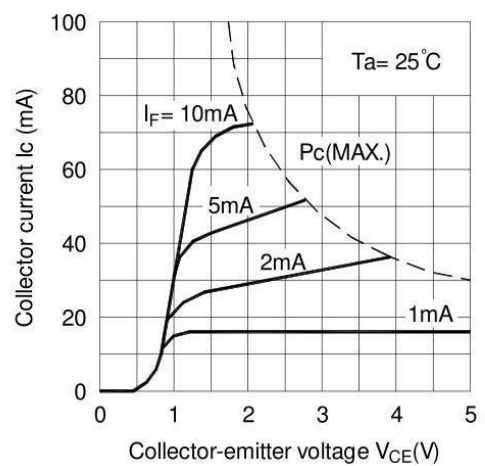


Fig.7 Relative Current Transfer Ratio vs. Ambient Temperature

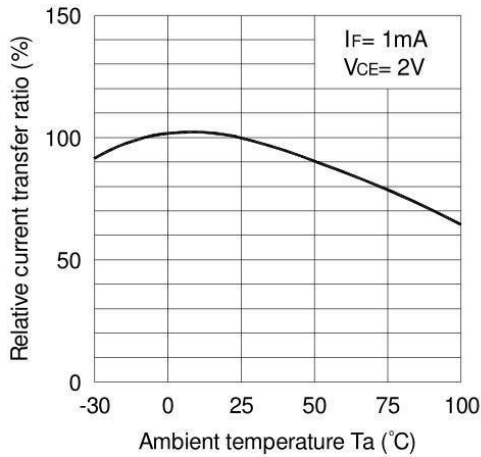


Fig.8 Collector-emitter Saturation Voltage vs. Ambient Temperature

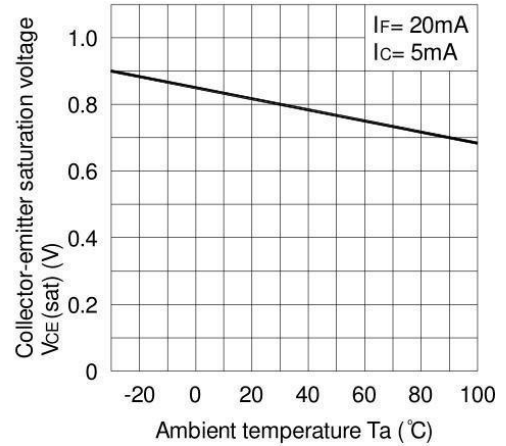


Fig.9 Collector Dark Current vs. Ambient Temperature

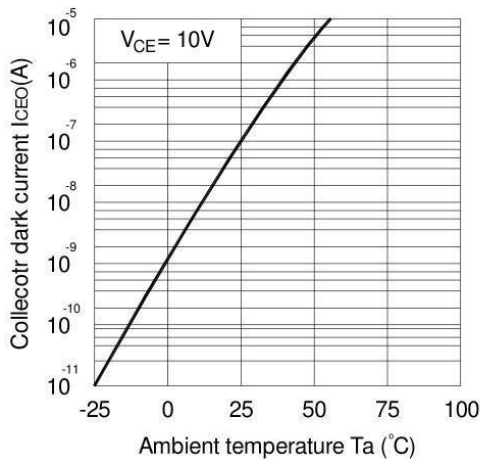


Fig.10 Response Time vs. Load Resistance

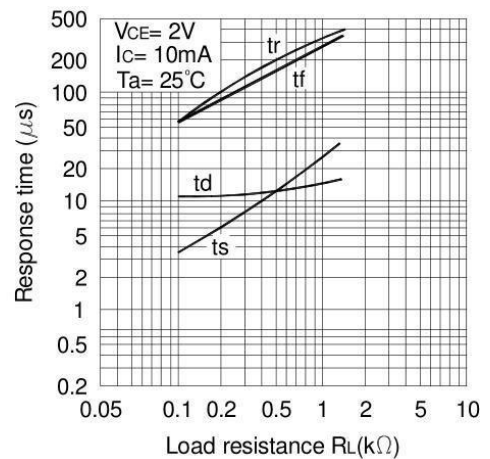
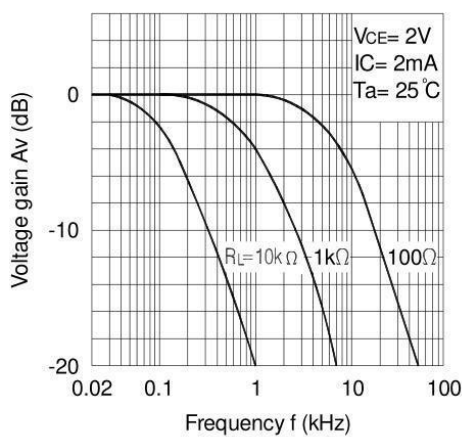
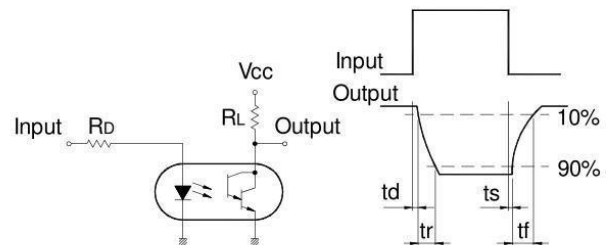


Fig.11 Frequency Response



Test Circuit for Response Time



Test Circuit for Frequency Response

